

SN54LV32, SN74LV32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCLS188C – FEBRUARY 1993 – REVISED APRIL 1996

- **EPIC™ (Enhanced-Performance Implanted CMOS) 2-μ Process**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} , $T_A = 25^\circ\text{C}$**
- **Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} , $T_A = 25^\circ\text{C}$**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ($C = 200\text{ pF}$, $R = 0$)**
- **Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs**

description

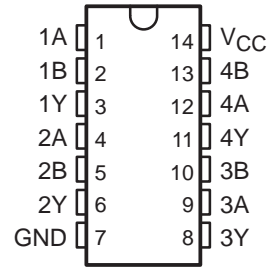
These quadruple 2-input positive-OR gates are designed for 2.7-V to 5.5-V V_{CC} operation.

The 'LV32 perform the Boolean function $Y = A + B$ or $Y = \overline{\overline{A} \cdot \overline{B}}$ in positive logic.

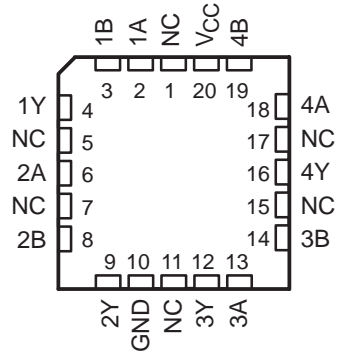
The SN74LV32 is packaged in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV32 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LV32 is characterized for operation from -40°C to 85°C .

SN54LV32 . . . J OR W PACKAGE
SN74LV32 . . . D, DB, OR PW PACKAGE
(TOP VIEW)



SN54LV32 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L



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**TEXAS
INSTRUMENTS**

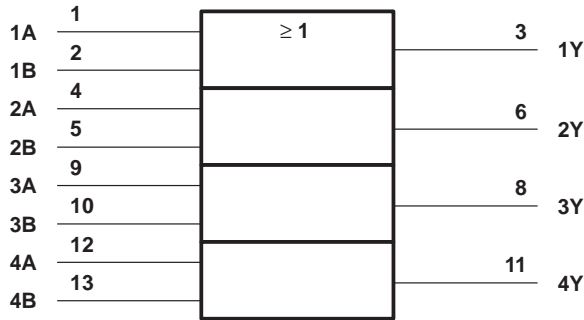
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logic symbol†



logic diagram, each gate (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, DB, J, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): D package	1.25 W
DB or PW package	0.5 W
Storage temperature range, T_{stg}	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 7 V maximum.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

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recommended operating conditions (see Note 4)

		SN54LV32		SN74LV32		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2.7	5.5	2.7	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		2		V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		3.15		
V_{IL}	Low-level input voltage	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		0.8		V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		1.65		
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		-6		mA
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		-12		
I_{OL}	Low-level output current	$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		6		mA
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		12		
$\Delta t/\Delta v$	Input transition rise or fall rate	0	100	0	100	ns/V
T_A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}^\dagger	SN54LV32			SN74LV32			UNIT	
			MIN	TYP	MAX	MIN	TYP	MAX		
V_{OH}	$I_{OH} = -100\ \mu\text{A}$	MIN to MAX	$V_{CC}-0.2$			$V_{CC}-0.2$			V	
	$I_{OH} = -6\ \text{mA}$	3 V	2.4			2.4				
	$I_{OH} = -12\ \text{mA}$	4.5 V	3.6			3.6				
V_{OL}	$I_{OL} = 100\ \mu\text{A}$	MIN to MAX	0.2			0.2			V	
	$I_{OL} = 6\ \text{mA}$	3 V	0.4			0.4				
	$I_{OL} = 12\ \text{mA}$	4.5 V	0.55			0.55				
I_I	$V_I = V_{CC}$ or GND	3.6 V	± 1			± 1			μA	
		5.5 V	± 1			± 1				
I_{CC}	$V_I = V_{CC}$ or GND	$I_O = 0$	3.6 V	20			20			μA
			5.5 V	20			20			
ΔI_{CC}	One input at $V_{CC} - 0.6\text{ V}$	One input at $V_{CC} - 0.6\text{ V}$	3 V to 3.6 V			500			μA	
C_i	$V_I = V_{CC}$ or GND	3.3 V	2.5			2.5			pF	
		5 V	2			2				

† For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

switching characteristics over recommended operating free-air temperature range, $C_L = 50\ \text{pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LV32						UNIT		
			$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$				$V_{CC} = 2.7\text{ V}$	
			MIN	TYP	MAX	MIN	TYP	MAX		MIN	MAX
t_{pd}	A	Y	6	10	9	13	16	16	ns		

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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

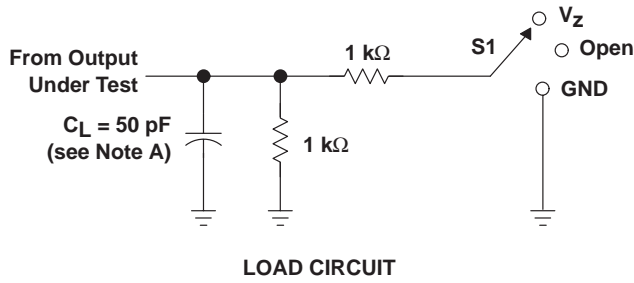
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74LV32						UNIT		
			$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$			$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$				$V_{CC} = 2.7 \text{ V}$	
			MIN	TYP	MAX	MIN	TYP	MAX		MIN	MAX
t_{pd}	A	Y	6	10		9	13		16	ns	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance per gate	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	3.3 V	23	pF
			5 V	27	

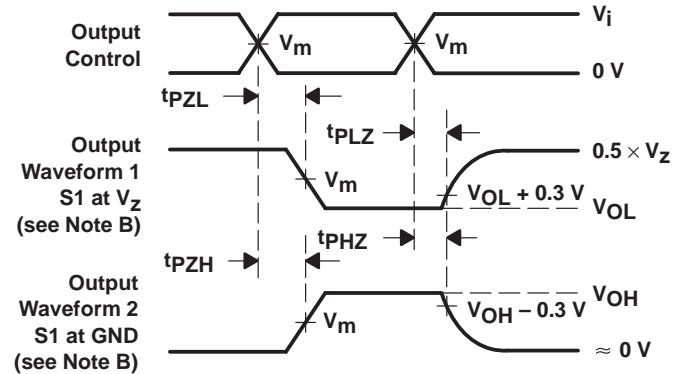
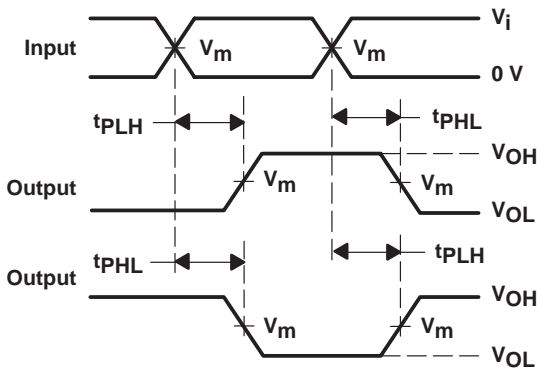
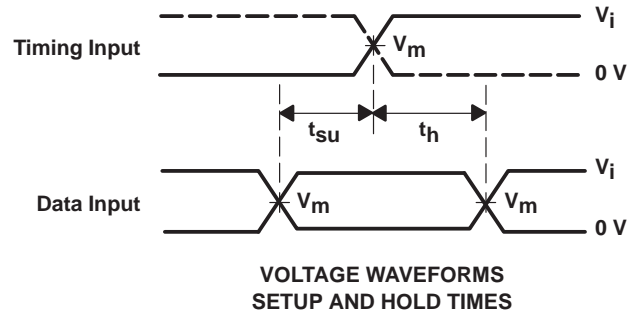
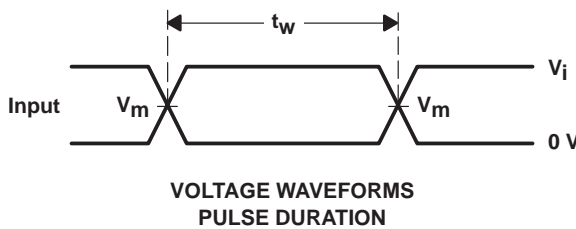


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _Z
t _{PHZ} /t _{PZH}	GND

WAVEFORM CONDITION	V _{CC} = 4.5 V to 5.5 V	V _{CC} = 2.7 V to 3.6 V
V _m	0.5 × V _{CC}	1.5 V
V _i	V _{CC}	2.7 V
V _Z	2 × V _{CC}	6 V



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
 D. The outputs are measured one at a time with one transition per measurement.
 E. t_{pLZ} and t_{pHZ} are the same as t_{dis}.
 F. t_{pZL} and t_{pZH} are the same as t_{en}.
 G. t_{pLH} and t_{pHL} are the same as t_{pd}.

Figure 1. Load Circuit and Voltage Waveforms

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